## **UP SuperServer SYS-521C-NR**



## **Key Applications**

Cloud Computing, Data Center Optimized, Network Appliance, Al inferencing, ML training, Database/Storage,

## **Key Features**

- Single Socket E (LGA-4677) 4th Gen Intel® Xeon® Scalable processors. Up to 350W TDP;
- Intel® C741 Chipset;
- 16 DIMMs; Supports 3DS DDR5 RDIMM. Up to 4800 MT/s;
- 2 PCIe 5.0 x16 FHFL + 2 PCIe 5.0 x16 FHHL (OR) 4 PCIe 5.0 x8 FHFL and 2 PCIe 5.0 x16 FHHL; 1 PCIe 5.0 x16 AIOM NIC(OCP 3.0); 2 PCIe 3.0 x2 NVMe M.2;
- Single AIOM with NCSI (OCP 3.0) for networking, 1 dedicated IPMI LAN;
- 12x front hot-swap 3.5" SATA3 drive bays (Optional 2 hybrid Gen5 NVMe), SAS3 with additional SAS controller card;
- Redundant Titanium 1200W Power Supplies;



Form Factor	2U Rackmount
	Enclosure: 437 x 89 x 648mm (17.2" x 3.5" x 25.5")
	Package: 678 x 290 x 876mm (26.7" x 11.4" x 34.5")
Processor	4th Gen Intel® Xeon® Scalable processors
	Single Socket LGA 4677 (Socket E) supported
	(Supports up to 350W TDP CPUs (Aircooled))
System Memory	16 DIMM slots
Drive Bays	12x 3.5" NVMe/SATA/SAS drive bays; 2x 3.5" NVMe hybrid;
Expansion Slots	4 PCIe 5.0 x8 FHFL slot(s)
	2 PCIe 5.0 x16 FHHL slot(s)
	Note:
	AIOM slot shares PCIe lanes with NVMe drives. Acronyms: (FH = Full Height, LP = Low Profile, FL = Full Length, HL =
	Half Length)
On-Board Devices	SATA: SATA3 (6Gbps); RAID 0/1/5/10 support
	NVMe: NVMe
	Chipset: Intel® C741
	Network Connectivity: Via AIOM
	IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
	iPMI 2.0 With Virtual media over LAN and KVM-over-LAN support
Input / Output	SATA: 12 SATA (6Gbps) port(s)
	LAN: 1 RJ45 Dedicated IPMI LAN port
	USB: 2 USB 3.2 Gen 1 port(s) (2 rear)
	2 USB 2.0 port(s) (2 headers)
	Video: 1 VGA port(s)



3x (8cm x 8cm x 3.8cm) heavy duty fan(s)

Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F)

Non-operating Temperature: -30°C to 60°C (-22°F to 140°F)

Operating Relative Humidity: 8% to 80% (non-condensing)

Non-operating Relative Humidity: 8% to 90% (non-condensing)

Super X13SEDW-F

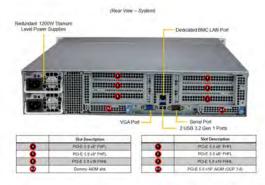
CSE-LA26TS-R1K23AWP1

System Cooling

Operating Environment

Motherboard

Chassis



\* Detail Configuration Exact lanes depend on the system basing

Power Supply	1U 1200W/1000W Titanium Power Supply W/PMbus W76xL336xH40mm
	Dimension (W x H x L): 76 x 40 x 336 mm
	Output Type: 19 Pairs Gold Finger Connector
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
Management	NMI; SUM; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; Redfish API; IPMI2.0
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory
	8 Phase-switching voltage regulator
	FAN: Fans with tachometer monitoring
	Status monitor for speed control
	Pulse Width Modulated (PWM) fan connectors
	Temperature: Monitoring for CPU and chassis environment
	Thermal Control for fan connectors
Dimensions and Weight	Height: 3.5" (89 mm)
	Width: 17.2" (437 mm)
	Depth: 25.5" (648 mm)
	Gross Weight: 59 lbs (26.76 kg)
	Net Weight: 33 lbs (15 kg)
	Packaging: 11.4" (H) x 26.7" (W) x 34.5" (D)
	Available Color: Black front & sliver body